

200G QSFP56 Direct Attach Passive Copper Cable

Features

- Compatible with IEEE 802.3bj and IEEE 802.3cd
- In accordance with the paging function in the protocol SFF-8636,
 paging can be selected 00H or 02H in 127 bytes
- Supports aggregate data rates of 200Gbps(PAM4)
- Optimized construction to minimize insertion loss and cross talk
- Backward compatible with existing QSFP+ connectors and cages
- Pull-to-release slide latch design
- 26AWG through 30AWG cable
- Straight and break out assembly configurations available
- Customized cable braid termination limits EMI radiation
- Customizable EEPROM mapping for cable signature
- RoHS compliant

Applications

- Switches, servers and routers
- Data Center networks
- Storage area networks
- High performance computing
- Telecommunication and wireless
 infrastructure
- Medical diagnostics and networking
- Test and measurement equipment

Compliance

- 200G Ethernet (IEEE 802.3cd)
- SFF-8665
- 108-32081 QSFP28 Copper Module Direct Attach Cable Assembly



Description

QSFP56 passive copper cable assembly feature eight differential copper pairs, providing four data transmission channels at s peeds up to 56Gbps(PAM4) per channel, and meets 200G Ethernet requirements. Available in a broad rang of wire gauges-from 26AWG through 30AWG-this 200G copper cable assembly features low insertion loss and low cross talk.

QSFP56 uses PAM4 signals for transmission, which doubles the rate. However, there are more stringent requirements for cable insertion loss. For detailed requirements, please see High Speed Characteristics.

Designed for applications in the data center, networking and telecommunications markets that require a high speed, reliable cable assembly, this next generation product shares the same mating interface with QSFP+ form factor, making it backward compatible with existing QSFP ports.

Absolute Maximum Ratings

Table1-Absolute Maximum Ratings						
Parameter	Symbol	Min.	Typical	Max.	Unit	Note
Storage Temperature	TSTG	-40	-	+85	°C	
Operating Case Temperature	Тс	0		+70	°C	
Power Supply Voltage	VCC3	3.14	3.3	3.47	٧	
Data Rate Per Lane		1	-	28	Gb/s	

High Speed Characteristics

Table2-High Speed Characteristics						
Parameter	Symbol	Min.	Typical	Max.	Unit	Note
Differential Impedance	TDR	90	100	110	Ω	
Insertion loss	SDD21	-16.06			dB	At 13.28 GHz
Differential Return Loss	SDD11			See1	dB	At 0.05 to 4.1 GHz
Differential Neturn 2055	SDD22			See 2	dB	At 4.1 to 19 GHz
Common-mode to common-mode output return loss	SCC11 SCC22			-2	dB	At 0.2 to 19 GHz
Differential to common-mode	SCD11			See 3		At 0.01 to 12.89 GHz
return loss	SCD22			See 4	dB	At 0.01 to 12.89 GHz
D:(() 1 M				-10		At 0.01 to 12.89 GHz
Differential to common Mode	SCD21-IL			See 5	dB	At 12.89 to 15.7 GHz
Conversion Loss				-6.3		At 15.7 to 19 GHz



Notes:

Reflection Coefficient given by equation SDD11(dB) \leq -16.5 + 2 \times SQRT(f), with f in GHz

Reflection Coefficient given by equation SDD11[dB] \leq -10.66 + 14 \times log10[f/5.5], with f in GHz

Reflection Coefficient given by equation SCD11(dB) \leq -22 + (20/25.78)*f, with f in GHz

Reflection Coefficient given by equation SCD11(dB) \leq -15 + (6/25.78)*f, with f in GHz

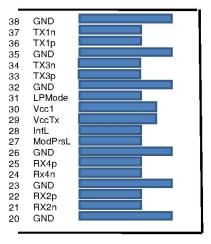
Reflection Coefficient given by equation SCD21(dB) \leq -27 + (29/22)*f, with f in GHz

Pin Descriptions

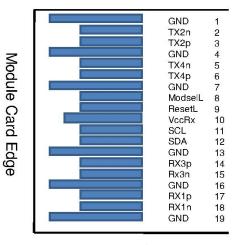
Table	Table3- Pin Function Definition				
Pin	Logic	Symbol	Description	Note	
1		GND	Ground	1	
2	CML-I	Tx2n	Transmitter Inverted Data Input		
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input		
4		GND	Ground	1	
5	CML-I	Tx4n	Transmitter Inverted Data Input		
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input		
7		GND	Ground	1	
8	LVTTL-I	ModSelL	Module Select		
9	LVTTL-I	ModSelL	Module Select		
10		Vcc Rx	+3.3V Power Supply Receiver	2	
11	LVCMOS-I/O	SCL	2-wire serial interface clock		
12	LVCMOS-I/O	SDA	2-wire serial interface data		
13		GND	Ground	1	
14	CML-0	Rx3p	Receiver Non-Inverted Data Outpu		
15	CML-0	Rx3n	Receiver Inverted Data Output		
16		GND	Ground	1	
17	CML-0	Rx1p	Receiver Non-Inverted Data Output		
18	CML-0	Rx1p	Receiver Inverted Data Output		
19		GND	Ground	1	
20		GND	Ground	1	
21	CML-0	Rx2n	Receiver Inverted Data Output		
22	CML-0	Rx2p	Receiver Non-Inverted Data Output		
23		GND	Ground		
24	CML-0	Rx4n	Receiver Inverted Data Output		
25	CML-0	Rx4p	Receiver Non-Inverted Data Output Ground		



26		GND	Ground	1
27	LVTTL-0	ModPrsL	Module Present	
28	LVTTL-0	IntL	Interrupt	
29		Vcc Tx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTL-I	LPMode	Low Power Mode	
32		GND	Ground	1
33	CML-I	Тх3р	Transmitter Non-Inverted Data Input	
34	CML-I	Tx3n	Transmitter Inverted Data Input	
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	
37	CML-I	Tx1n	Transmitter Inverted Data Input	
38		GND	Ground	1



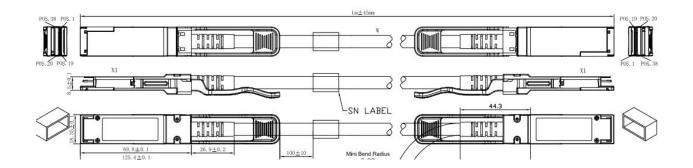
Top Side Viewed From Top



Bottom Side Viewed From Bottom



Mechanical Specifications



Length (m)	Cable AWG
0.5/1/1.5	30
2	26/30
3	26

Regulatory Compliance

Feature	Test Method	Performance	
Electrostatic Discharge (ESD) to the Electrical Pins	MIL-STD-883C Method 3015.7	Class 1(→2000 Volts)	
Electromagnetic Interference(EMI)	FCC Class B		
	CENELEC EN55022 Class B	Compliant with Standards	
	CISPR22 ITE Class B		
RF Immunity(RFI)	IEC61000-4-3	Typically Show no Measurable Effect from a 10V/m Field Swept from 80 to 1000MHz	
	RoHS Directive 2011/65/EU and it's	a Tov/III Fleta Swept Hoffl oo to TooolMHZ	
RoHS Compliance	Amendment Directives 6/6	RoHS 6/6 compliant	



Further Information:

Web www.naddod.com

Email For order requirements: sales@naddod.com For cooperation: agency@naddod.com

For customer service: support@naddod.com For other informations: info@naddod.com

For technical support: tech@naddod.com

Disclaimer

- 1. We are committed to continuous product improvement and feature upgrades, and the contents contained in this manual are subject to change without notice.
- 2. Nothing herein should be construed as constituting an additional warranty.
- 3. NADDOD assumes no responsibility for the use or reliability of equipment or software not provided by NADDOD. Copyright © NADDOD.COM All Rights

NADDOD - Building an Intelligent World with Everything Connected HPC | AI | Datacenter | Enterprise | Telecom